

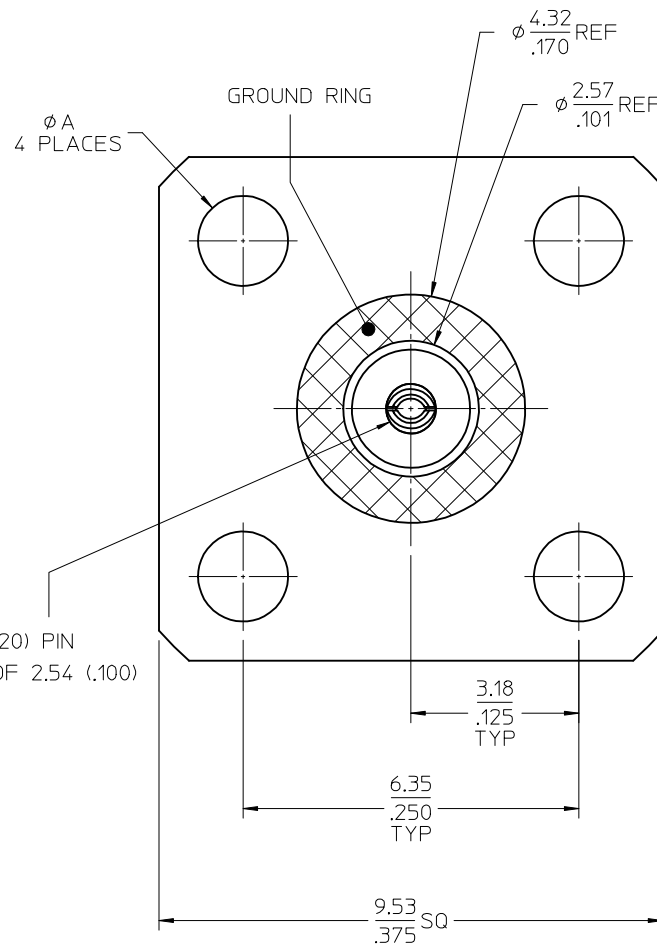
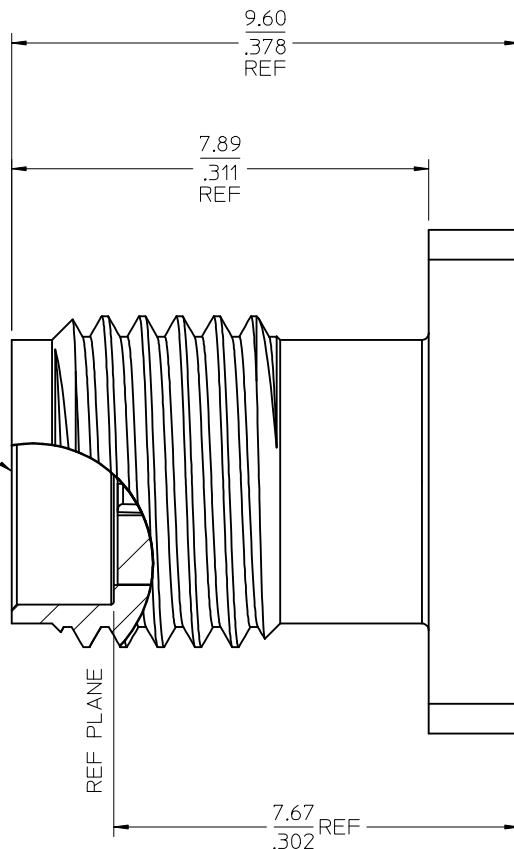
MATERIALS AND FINISHES

BODY: STAINLESS STEEL
PASSIVATED

CONTACT: BERYLLIUM COPPER
PLATED GOLD

INSULATOR: TEFLON

SMA JACK



73251-0841	2.06 / .081
73251-0840	1.70 / .067
PART NO.	MM / IN
	DIM A

CHG: REDREW IN SD MAX PIN DEPTH WAS .110 EC NO: URF2013-0626 DRWN: JWIENER 2013/05/08 CHKD: SSS 2013/05/08 APPR: JWIENER 2013/05/09 A2	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM/IN		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION				
				mm	INCH	DRAWN BY	DATE	TITLE	METRIC				
			4 PLACES	± ---	± ---	JWIENER	2013/05/08	SMA JACK FIELD REPLAC. 4 HOLE FLANGE .020 PIN SMA-JR/F EWR-1594					
			3 PLACES	± ---	± ---	CHECKED BY	DATE						
			2 PLACES	± ---	± ---	SSS	2013/05/08						
			1 PLACE	± ---	± ---	APPROVED BY	DATE	MOLEX INCORPORATED					
			ANGULAR ± 2 °		JWIENER	2013/05/09							
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-73251-084		SHEET NO. 1 OF 1				
					SIZE C	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							